

ABSTRACT

An arrangement for cooling an electronic assembly includes a circuit board, an enclosure member and at least one electromechanical actuator. The circuit board has a first surface, a second surface, and at least a first heat-generating element secured to the first surface. The circuit board further comprises at least one aperture extending between the first surface and the second surface. The enclosure member is secured to the circuit board so as to form a fluid tight barrier of a compartment defined at least in part by the enclosure member. The compartment includes a first subcompartment defined at least in part by the first surface and the enclosure member and a second subcompartment defined at least in part by the second surface and the enclosure member. The at least one electromechanical actuator is secured within the fluid type barrier and is operable to generate a flow movement in the direction of the at least one aperture when liquid is disposed in the fluid tight barrier.